



Features

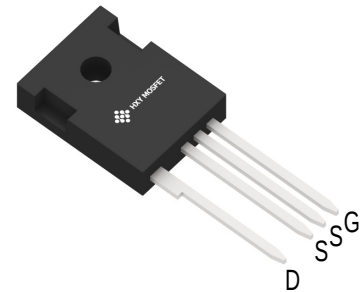
- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitance
- Easy to Parallel and Simple to Drive

Benefits

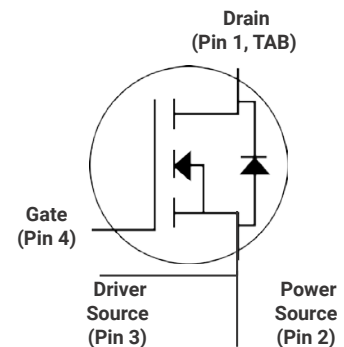
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

Applications

- Renewable Energy
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies



TO-247-4L



Ordering Part Number	Package	Qty(PCS)
G3R75MT12K	T0247-4L	30

Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{DSmax}	Drain-Source Voltage	1200	V	$V_{GS}=0V, I_D=100\mu A$	
V_{GSmax}	Gate-Source Voltage	-10/+25	V	Absolute maximum values	
V_{GSop}	Gate-Source Voltage	-5/+20	V	Recommended operational values	
I_D	Continuous Drain Current	36	A	$V_{GS}=20V, T_c=25^\circ\text{C}$	Fig. 19
		24		$V_{GS}=20V, T_c=100^\circ\text{C}$	
$I_{D(pulse)}$	Pulsed Drain Current	80	A	Pulse width t_p limited by T_{Jmax}	Fig. 22
P_D	Power Dissipation	192	W	$T_c=25^\circ\text{C}, T_J=150^\circ\text{C}$	Fig. 20
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to +150	$^\circ\text{C}$		
T_L	Solder Temperature, 1.6mm from case for 10s	260	$^\circ\text{C}$		
M_d	Mounting Torque, (M3 or 6-32 screw)	1	Nm		
		8.8	lbf-in		



Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless other

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200	/	/	V	$V_{GS}=0V, I_D=100\mu A$	
$V_{GS(th)}$	Gate Threshold Voltage	2.0	2.4	4.0	V	$V_{DS}=V_{GS}, I_D=5mA$	Fig. 11
		/	1.8	/		$V_{DS}=V_{GS}, I_D=5mA, T_J=150^\circ\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current	/	1	100	μA	$V_{DS}=1200V, V_{GS}=0V$	
I_{GSS+}	Gate-Source Leakage Current	/	10	250	nA	$V_{DS}=0V, V_{GS}=25V$	
I_{GSS-}	Gate-Source Leakage Current	/	10	250	nA	$V_{DS}=0V, V_{GS}=-10V$	
$R_{DS(on)}$	Drain-Source On-State Resistance	/	80	98	m Ω	$V_{GS}=20V, I_D=20A$	Fig. 4,5,6
		/	140	/		$V_{GS}=20V, I_D=20A, T_J=150^\circ\text{C}$	
g_{fs}	Transconductance	/	11.2	/	S	$V_{DS}=20V, I_{DS}=20A$	Fig. 7
		/	11.3	/		$V_{DS}=20V, I_{DS}=20A, T_J=150^\circ\text{C}$	
C_{iss}	Input Capacitance	/	1475	/	pF	$V_{GS}=0V$	Fig. 17,18
C_{oss}	Output Capacitance	/	94	/		$V_{DS}=1000V$	
C_{rss}	Reverse Transfer Capacitance	/	11	/		$f=1MHz$	
E_{oss}	C_{oss} Stored Energy	/	52	/	μJ	$V_{AC}=25mV$	Fig. 16
E_{ON}	Turn-On Switching Energy	/	564	/	mJ	$V_{DS}=800V, V_{GS}=-5V/20V$	
E_{OFF}	Turn-Off Switching Energy	/	260	/		$I_D=20A, R_{G(ext)}=2.5\Omega, L=200\mu H$	
$t_{d(on)}$	Turn-On Delay Time	/	9.3	/	ns	$V_{DS}=800V, V_{GS}=-5V/20V, I_D=20A$ $R_{G(ext)}=2.5\Omega, R_L=40\Omega$	
t_r	Rise Time	/	9.5	/			
$t_{d(off)}$	Turn-Off Delay Time	/	18	/			
t_f	Fall Time	/	7.6	/			
$R_{G(int)}$	Internal Gate Resistance	1	3.1	5.5	Ω	$f=1MHz, V_{AC}=25mV$	
Q_{GS}	Gate to Source Charge	/	24	/	nC	$V_{DS}=800V$	Fig. 12
Q_{GD}	Gate to Drain Charge	/	15	/		$V_{GS}=-5V/20V$	
Q_G	Total Gate Charge	/	79	/		$I_D=20A$	

Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	3.6	/	V	$V_{GS}=-5V, I_{SD}=10A$	Fig. 8,9,10
		3.3	/		$V_{GS}=-5V, I_{SD}=10A, T_J=150^\circ\text{C}$	
I_S	Continuous Diode Forward Current	/	44	A	$T_c=25^\circ\text{C}$	
t_{rr}	Reverse Recover Time	35	/	ns	$V_R=800V, I_{SD}=20A$	
Q_{rr}	Reverse Recovery Charge	91	/	nC		
I_{rrm}	Peak Reverse Recovery Current	4.5	/	A		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.6	/	$^\circ\text{C/W}$		Fig. 21
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	/	40			



Typical Performance

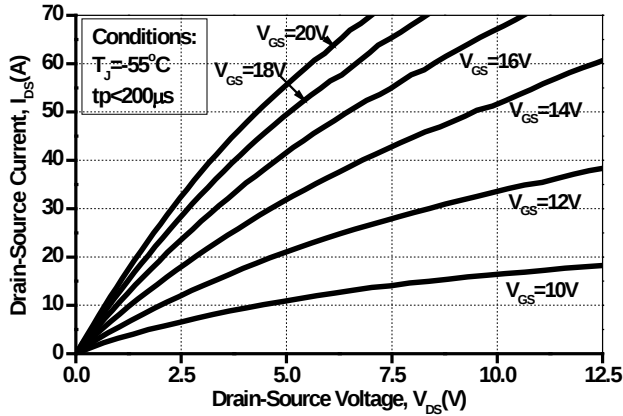


Figure 1. Output Characteristics $T_j = -55^\circ\text{C}$

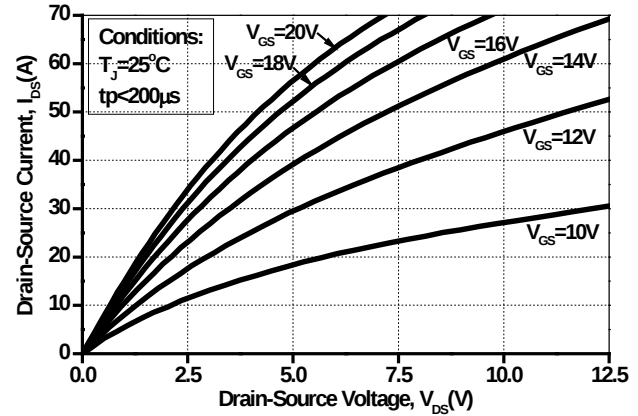


Figure 2. Output Characteristics $T_j = 25^\circ\text{C}$

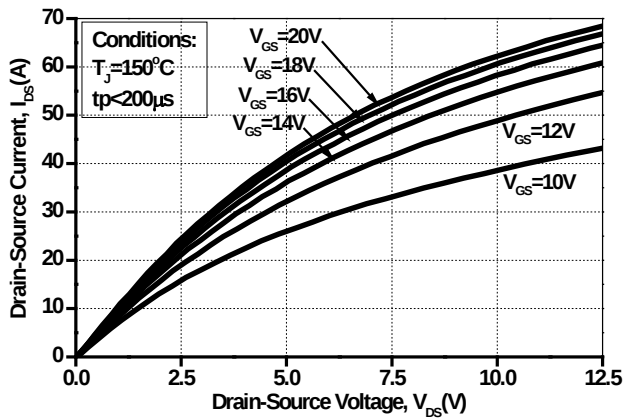


Figure 3. Output Characteristics $T_j = 150^\circ\text{C}$

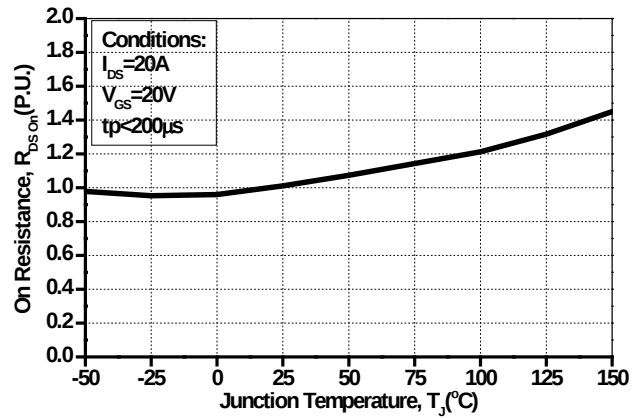


Figure 4. Normalized On-Resistance vs. Temperature

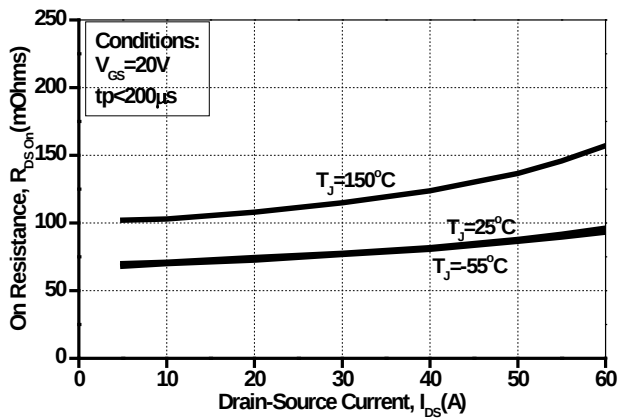


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

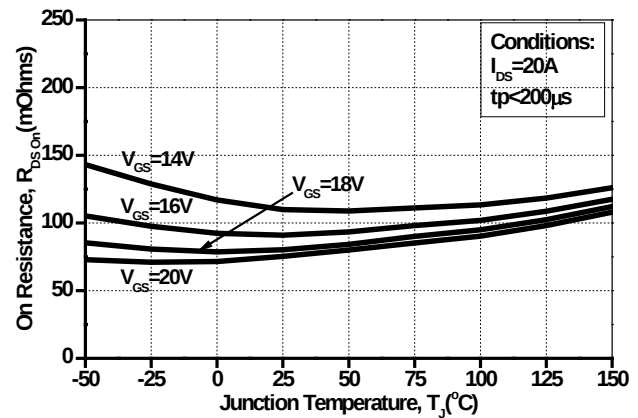


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage



Typical Performance

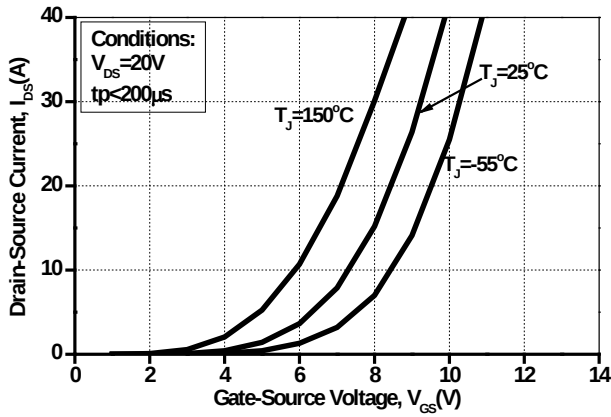


Figure 7. Transfer Characteristic for Various Junction Temperatures

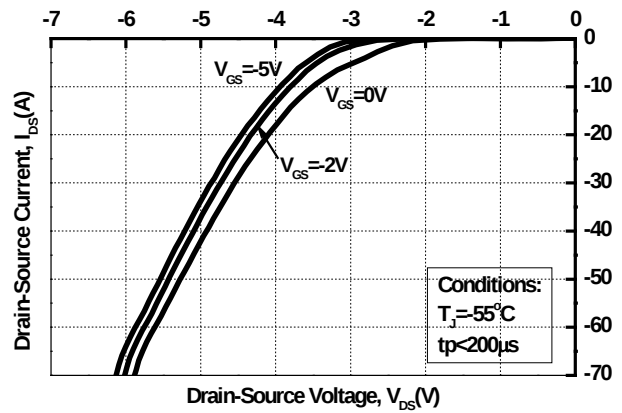


Figure 8. Body Diode Characteristic at -55°C

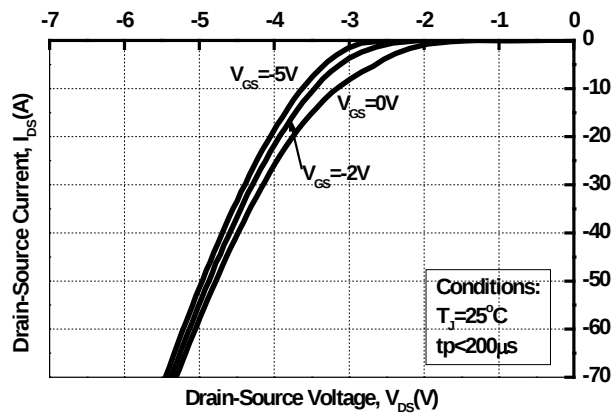


Figure 9. Body Diode Characteristic at 25°C

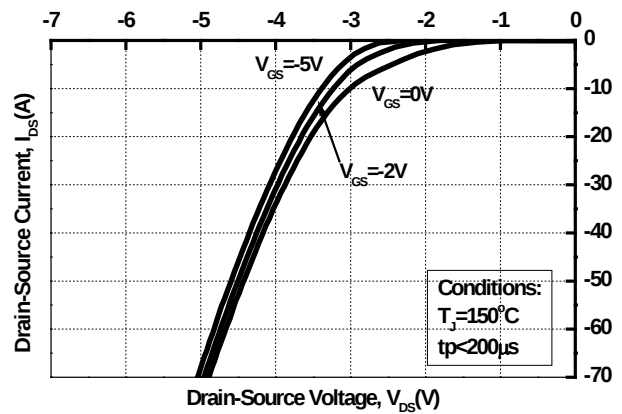


Figure 10. Body Diode Characteristic at 150°C

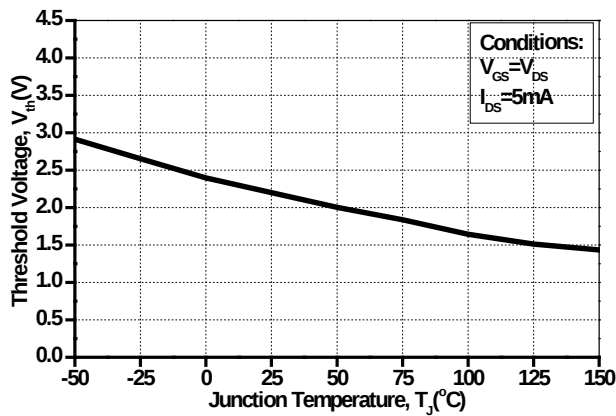


Figure 11. Threshold Voltage vs. Temperature

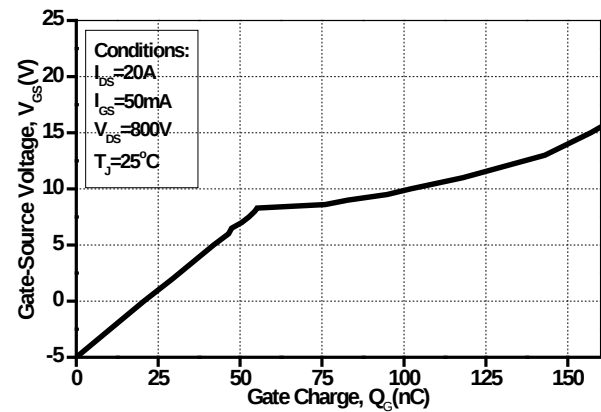


Figure 12. Gate Charge Characteristics



Typical Performance

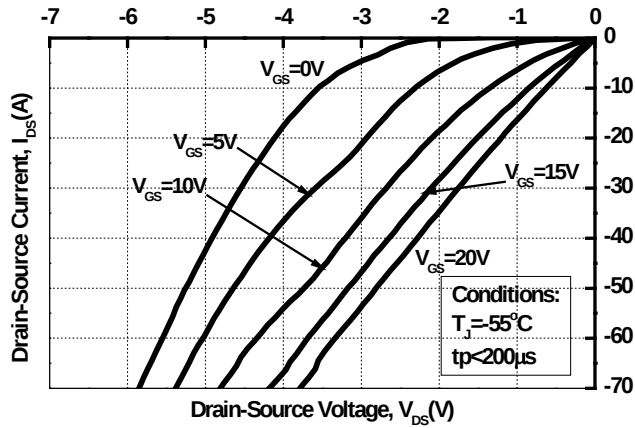


Figure 13. 3rd Quadrant Characteristic at -55 °C

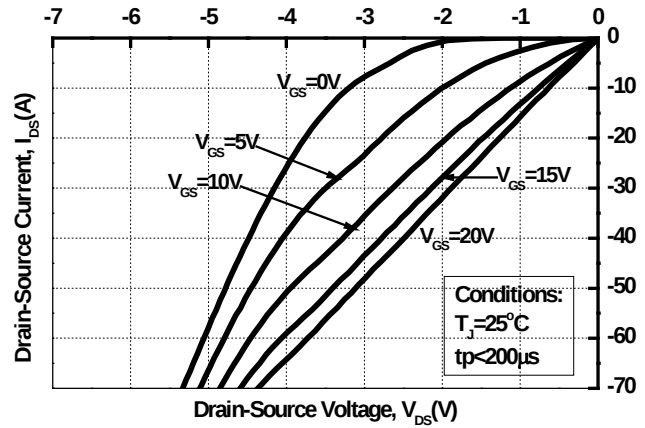


Figure 14. 3rd Quadrant Characteristic at 25 °C

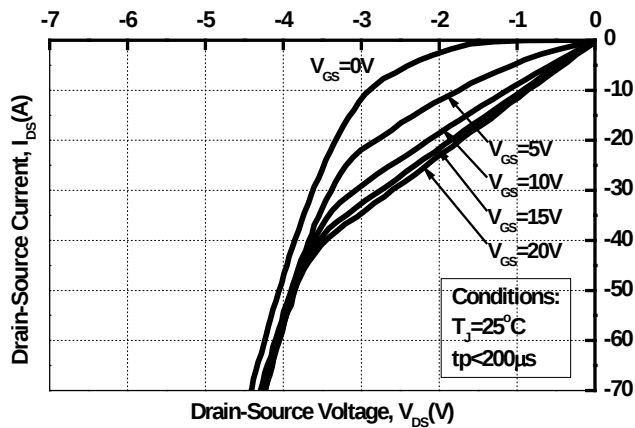


Figure 14. 3rd Quadrant Characteristic at 150 °C

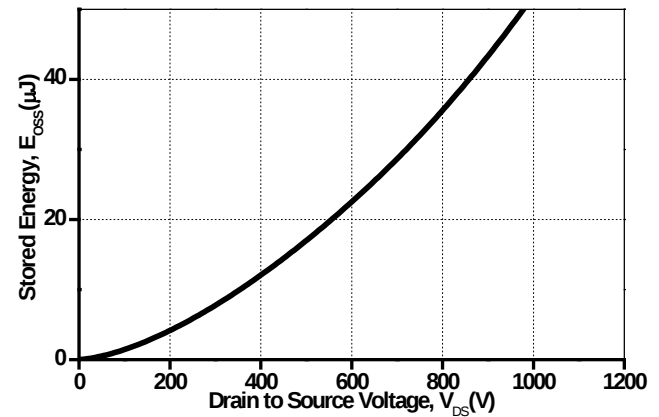


Figure 16. Output Capacitor Stored Energy

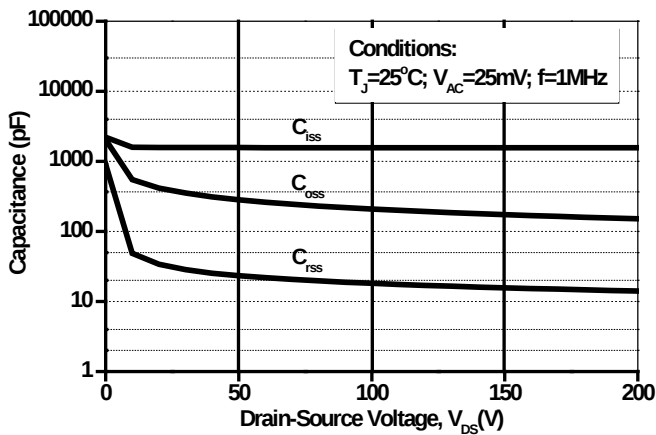


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

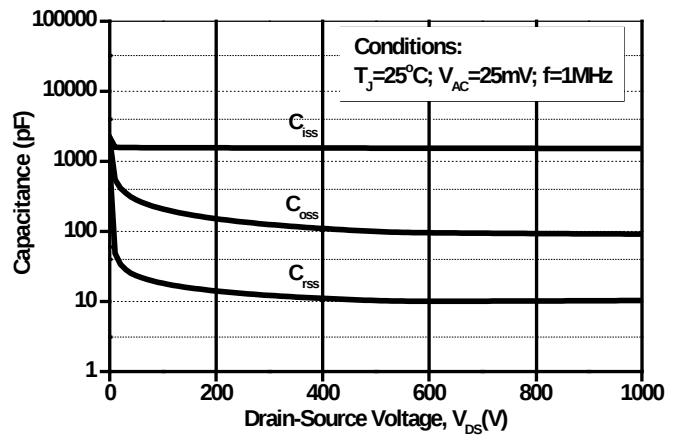


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1000V)



Typical Performance

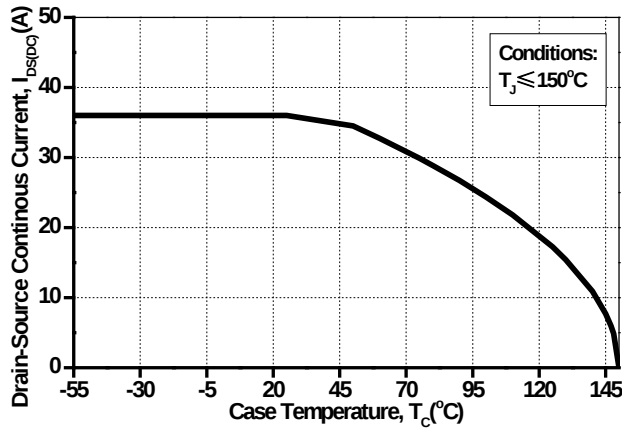


Figure 19. Continuous Drain Current Derating vs. Case Temperature

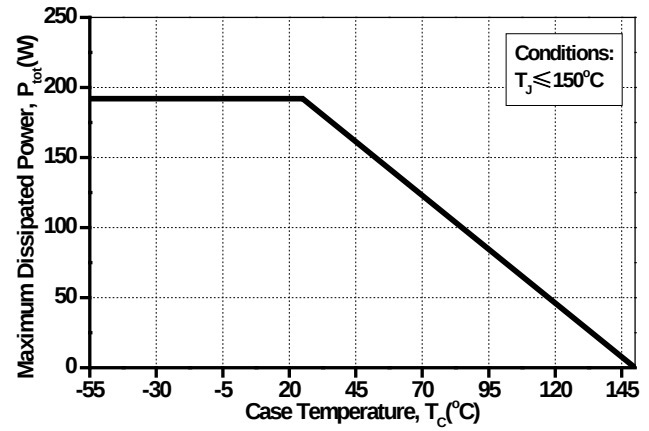


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

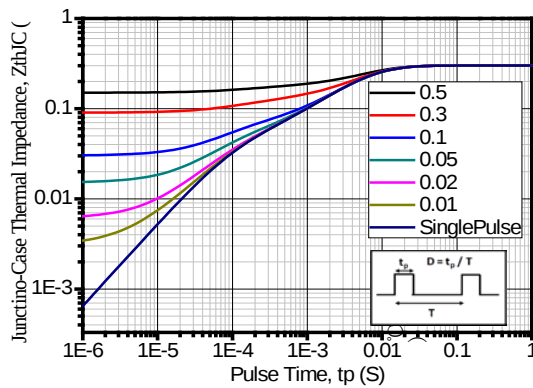


Figure 21. Transient Thermal Impedance (Junction - Case)

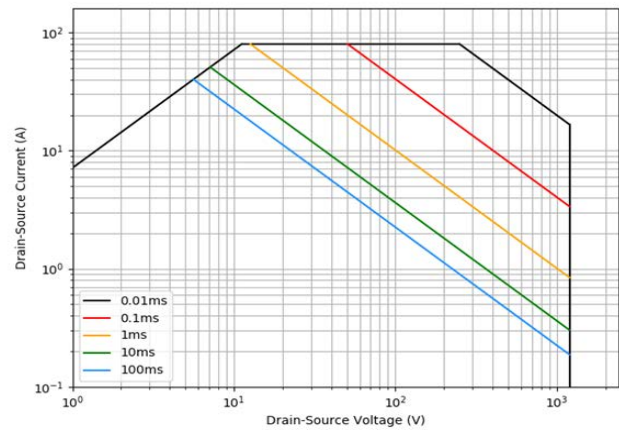


Figure22. Safe Operating Area



Test Circuit Schematic

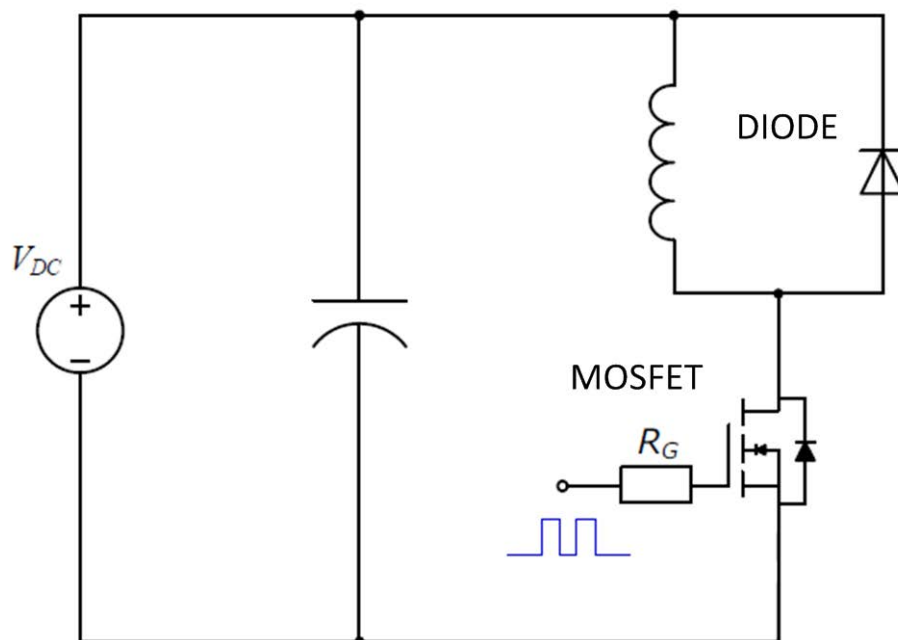
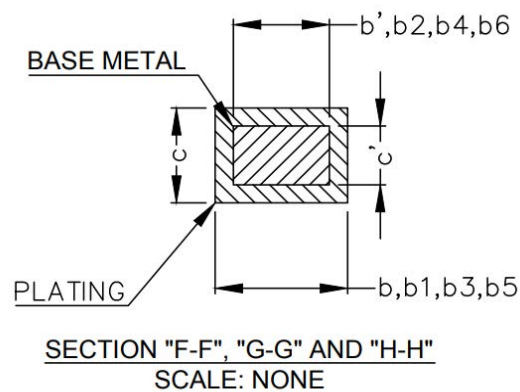
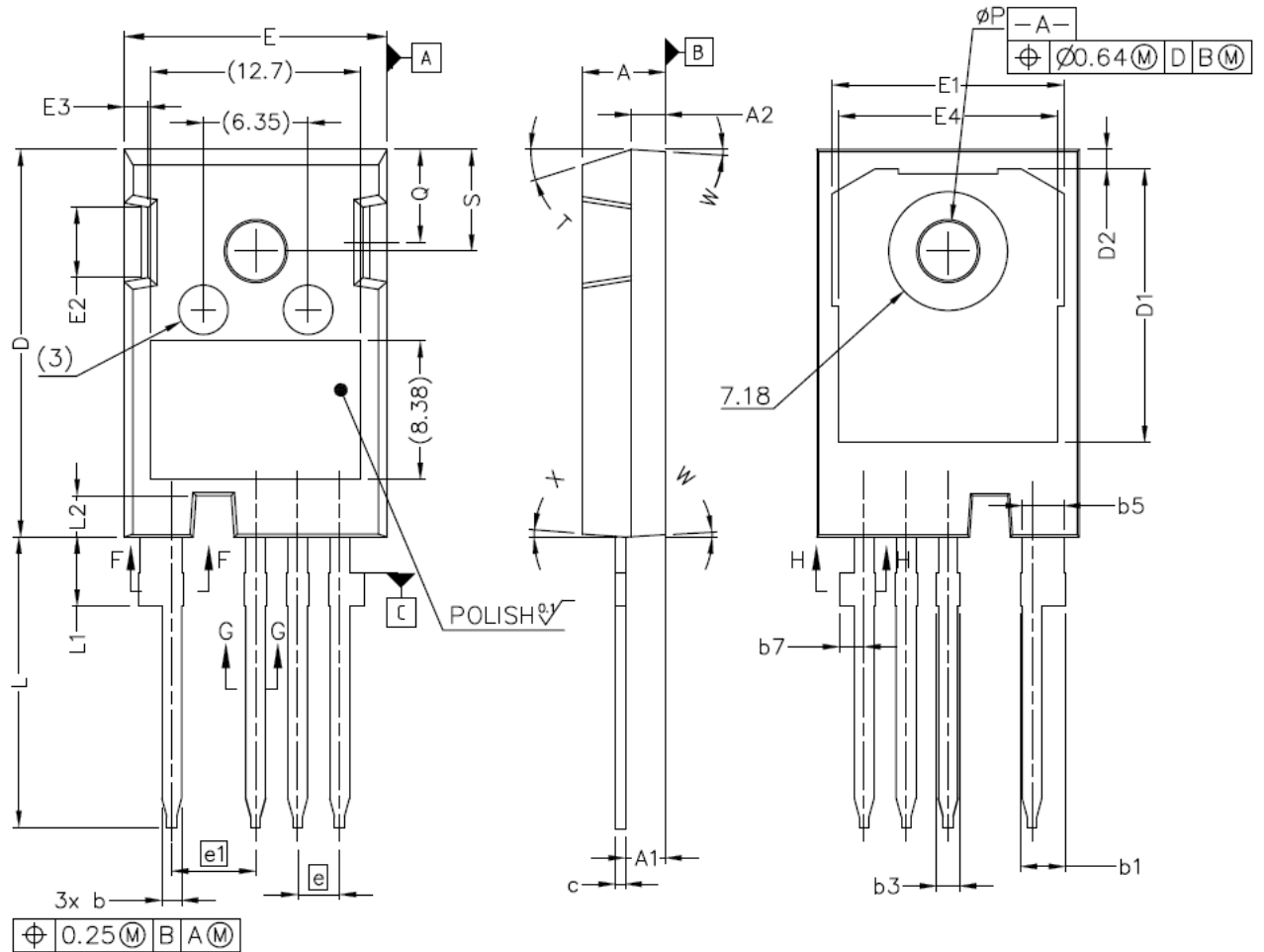


Figure 23. Clamped Inductive Switching
Waveform Test Circuit



Package Dimensions

Package T0247-4L





Package Dimensions

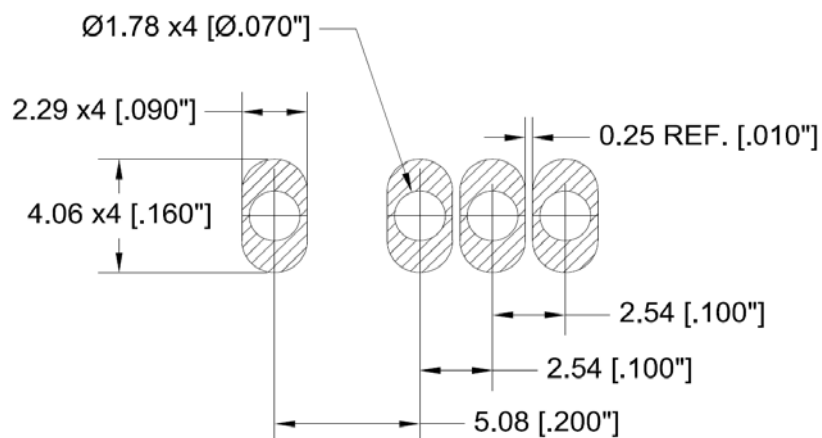
Package T0247-4L

NOTE ;

1. ALL METAL SURFACES: TIN PLATED, EXCEPT AREA OF CUT
2. DIMENSIONING & TOLERANCEING CONFIRM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE IN MILLIMETERS.
ANGLES ARE IN DEGREES.
4. 'N' IS THE NUMBER OF TERMINAL POSITIONS

SYM	MILLIMETERS	
	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b`	1.07	1.28
b	1.07	1.33
b1	2.39	2.94
b2	2.39	2.84
b3	1.07	1.60
b4	1.07	1.50
b5	2.39	2.69
b6	2.39	2.64
b7	1.30	1.70
c`	0.55	0.65
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13

SYM	MILLIMETERS	
	MIN	MAX
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	2.54 BSC	
e1	5.08 BSC	
N*	4	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
Ø P	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	





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